

MULTI-INNO TECHNOLOGY CO., LTD.

LCD MODULE SPECIFICATION

Model : MI1602K2

Revision	1.1
Engineering	
Date	
Our Reference	

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RECORDS OF REVISION

Date	Rev.	Description	Note	Page
2007/3/15	1.0	New Sample		
2009/10/15	1.1	Update Timing Characteristics and Display Command		13,14



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Note : For detailed information please refer to IC data sheet : <u>ST7066U,ST7065C</u>



1. SPECIFICATIONS

1.1 Features

ltem	Standard Value
Display Type	16 * 2 Characters
LCD Type	STN , Gray , Transflective , Positive , Normal Temp.
Driver Condition	1/16 Duty [,] 1/5 Bias
Viewing Direction	6 O'clock
Backlight	Yellow-Green LED B/L
Weight	11.0g
Interface	_
Other	_

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	53.0 (L) * 20.0 (w) * 8.6 (H)(Max)	mm
Viewing Area	36.0 (L) * 10.0 (w)	mm
Active Area	34.1 (L) * 7.4 (w)	mm
Dot Size	0.35 (L) * 0.33 (w)	mm
Dot Pitch	0.40 (L) * 0.38 (w)	mm

Note : For detailed information please refer to LCM drawing

1.3 Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply Voltage	V _{DD}	_	-0.3	7.0	V
LCD Driver Supply Voltage	V _{LCD}	_	Vdd-10.0	VDD+0.3	V
Input Voltage	V _{IN}	_	-0.3	V _{DD} +0.3	V
Operating Temperature	T _{OP}	Excluded B/L	0	50	°C
Storage Temperature	T _{ST}	Excluded B/L	-20	70	°C
Storage Humidity	H _D	Ta<40 °C	-	90	%RH



$V_{DD} = 5.0 \text{ V} \pm 10\% \text{ , } V_{SS} = 0 \text{V} \text{ , } \text{ Ta}$					/,Ta = 2	5 ℃
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Logic Supply Voltage	V _{DD}	_	4.5	5.0	5.5	V
"H" Input Voltage	Vih	_	0.7 Vdd	-	Vdd	V
"L" Input Voltage	V _{IL}		-0.3	-	0.6	V
"H" Output Voltage	V _{OH}	l _{OH} =-0.1mA	3.9	-	V _{DD}	V
"L" Output Voltage	V _{OL}	l _{OL} =0.1mA	-	-	0.4	V
Supply Current	I _{DD}	V _{DD} = 5.0 V	1.2	1.5	3.0	
Supply Current	I _{EE}	_	-	-	-	- mA
		0 °C	-	-	-	
LCM Driver Voltage	V _{OP}	25 ℃*1	4.2	4.4	4.7	V
		50 ℃	-	-	-	

1.4 DC Electrical Characteristics

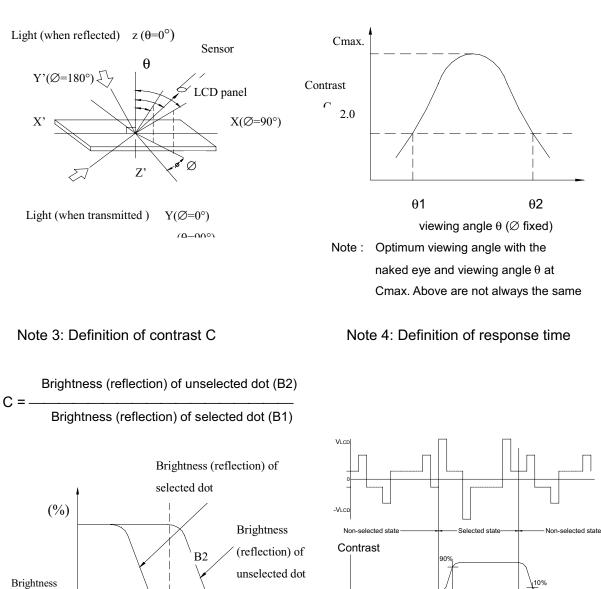
Note: *1. THE V_{OP} TEST POINT IS V_{DD} - $V_{\text{O}}.$

1.5 Optical Characteristics

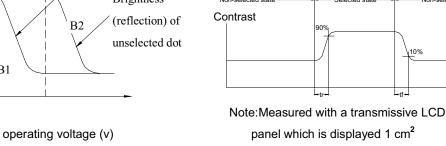
LCD Panel:1/16 Duty,1/5 Bias,V_{LCD} = 4.67 V,Ta = 25 $^\circ\!\mathrm{C}$

Item	Symbol	Conditions	Min.	Тур.	Max.	Reference
View Angle	θ	C <u>≥</u> 2.0, ∅ = 0°	40°	-	-	Notes 1 & 2
Contrast Ratio	С	$\theta = 5^{\circ}, \emptyset = 0^{\circ}$	5	7	-	Note 3
Response Time(rise)	tr	$\theta = 5^{\circ}, \emptyset = 0^{\circ}$	-	150 ms	-	Note 4
Response Time(fall)	tf	$\theta = 5^{\circ}, \emptyset = 0^{\circ}$	-	300 ms	-	Note 4





Note 1: Definition of angles θ and \emptyset





Note 2: Definition of viewing angles θ 1 and θ 2

tr : Response time (rise) tr : Response time (fall)

0

(reflection)

B1

Time



Ver 1.1

1.6 Backlight Characteristics

LCD Module with LED Backlight

Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	Ta =25℃	-	40	mA
Reverse Voltage	VR	Ta =25℃	-	8	V
Power Dissipation	PO	Ta =25 ℃	-	0.19	W
Operating Temperature	T _{OP}	-	-20	70	°C
Storage Temperature	T _{ST}	-	-30	80	°C
Solder Temp. for 3 Second	-	-	-	260	°C

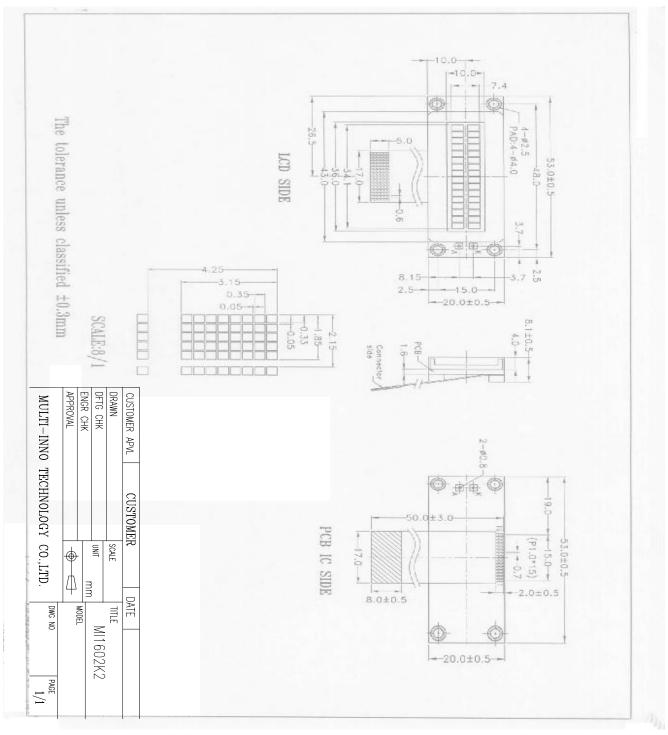
Electrical / Optical Characteristics

Symbol Conditions Min. Max. Unit Item Тур. Forward Voltage VF IF= 28mA 4.2 V -4.8 **Reverse Current** IR VR= 8 V 0.2 mΑ --Average Brightness cd/m^2 IV IF= 28mA 4 5 -(with LCD) IF= 28 mA Wavelength 570 λρ -nm Color Yellow-Green

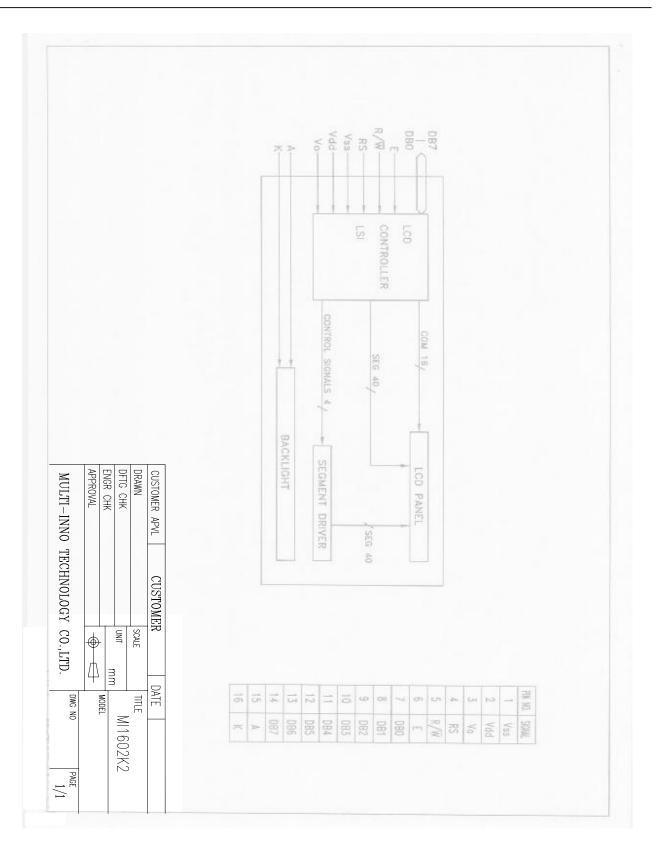


2. MODULE STRUCTURE

2.1 Counter Drawing





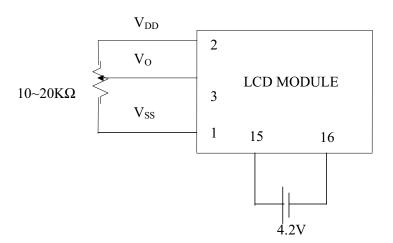




Pin No.	Symbol	Function
1	Vss	Signal ground (GND)
2	VDD	Power Supply for logic (VDD> Vss)
3	Vo	Operating Voltage for LCD (variable)
		Register selection input
4	RS	High = Data register
4	KS	Low = Instruction register (for write)
		Busy flag address counter (for read)
5		Read/Write signal input is used to select the read/write
5	R/W	mode. High = Read mode, Low = Write mode
6	Е	Start enable signal to read or write the data
		Four low order bi-directional three-state data bus lines.
7-10	DB0 ~ DB3	Used
/-10		for data transfer between the MPU and the LCD module.
		These four are not used during 4-bit operation.
		Four high order bi-directional three-state data bus lines.
11~14	DB4~DB7	Used for data transfer between the MPU and the LCD
11~14	DB4~DB/	module.
		DB7 can be used as a busy flag.
15	А	Power supply for LED backlight (+)
16	K	Power supply for LED backlight (-)

2.2 Interface Pin Description

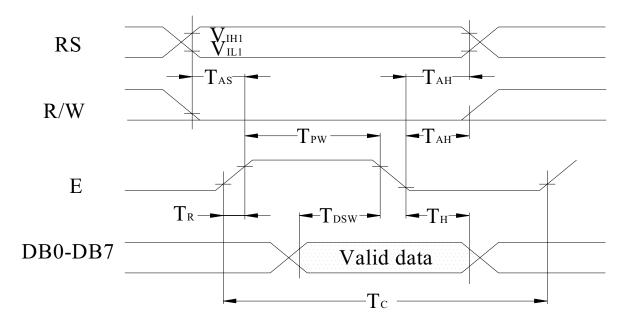
Contrast Adjust



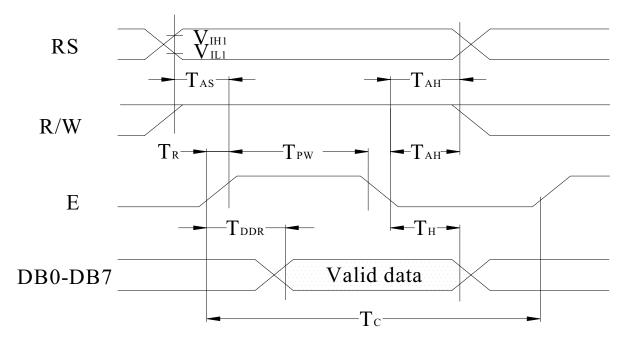


2.3 Timing Characteristics

• Writing data from MPU to ST7066U



• Reading data from ST7066U to MPU





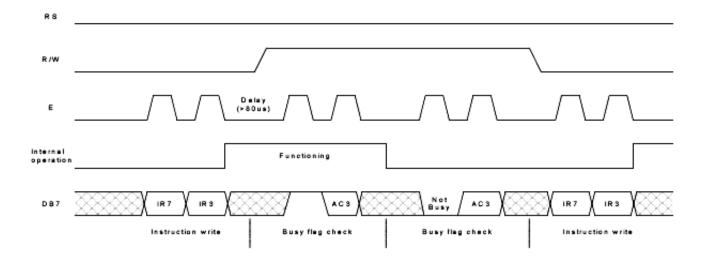
	$(VDD = +5V \pm 10\%, Ta)$,Ta=25°C)	
Symbol	Characteristics	Test Condition	Min.	Тур.	Max.	Unit
T _C	Enable Cycle Time	Pin E	1200	-	-	ns
T _{PW}	Enable Pulse Width	Pin E	140	-	-	ns
T_R, T_F	Enable Rise / Fall Time	Pin E	-	-	25	ns
T _{AS}	Address Setup Time	Pins: RS , RW,E	0	-	-	ns
T _{AH}	Address Hold Time	Pins :RS,RW,E	10	-	-	ns
T _{DSW}	Data Setup Time	Pins:DB0~DB7	40	-	-	ns
T _H	Data Hold Time	Pins:DB0~DB7	10	-	-	ns

• Write Mode (Writing data from MPU to ST7066U)

 Read Mode (Reading data from ST7066U to MPU) 						
				(VDD=	=+5V <u>+</u> 10%	,Ta=25°C)
Symbol	Characteristics	Test Condition	Min.	Тур.	Max.	Unit
T _C	Enable Cycle Time	Pin E	1200	-	-	ns
T _{PW}	Enable Pulse Width	Pin E	140	-	-	ns
T_R, T_F	Enable Rise / Fall Time	Pin E	-	-	25	ns
T _{AS}	Address Setup Time	Pins: RS , RW,E	0	-	-	ns
T _{AH}	Address Hold Time	Pins :RS,RW,E	10	-	-	ns
T _{DDR}	Data Setup Time	Pins:DB0~DB7	-	-	100	ns
T _H	Data Hold Time	Pins:DB0~DB7	10	-	-	ns

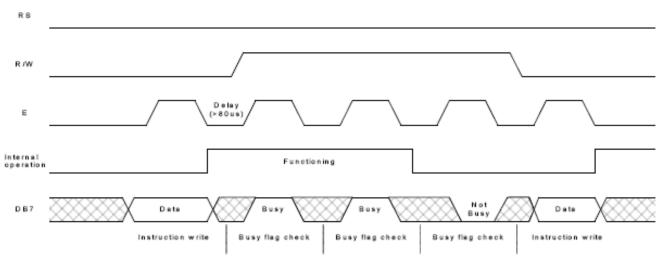


For 4-bit interface date, only four bus lines (DB4 to DB7) are used for transfer.



Example of busy flag check timing sequence

For 8-bit interface date, all eight bus lines (DB0 to DB7) are used .



Example of busy flag check timing sequence



	Instruction Code						Code					Description		
Instructions	RS R/W DI		DB	DB	DB	DB	DB	DB	DB	DB	Description	Time		
	RS	K/W	7	6	5	4	3	2	1	0		(270KHz)		
Clear											Write "20H" to DDRAM. and set			
Display	0	0	0	0	0	0	0	0	0	1	DDRAM address to "00H" from	1.52ms		
Display											AC.			
											Set DDRAM address to "00H"			
Return											from AC and return cursor to it's			
Home	0	0	0	0	0	0	0	0	1	×	original position if shifted.	1.52ms		
lionic											The contents of DDRAM are not			
											changed.			
											Sets cursor move direction and			
Entry Mode	0	0 0	0	0	0	0	0	1	I/D	S	specifies display shift. These	37118		
Set			Ū	Ũ							operations are performed during			
											data write and read .			
Display											D=1 : entire display on			
ON/OFF	0	0	0	0	0	0	1	D	C	B	C=1 : cursor on	37µs		
											B=1 : cursor position on			
Cursor or											Set cursor moving and display			
Display	0	0	0	0	0	1	S/C	R/L	×	×	shift control bit, and the direction,	37µs		
Shift			-								without changing of DDRAM			
											data.			
Function											DL: interface data is 8/4 bits			
Set	0	0	0	0	1	DL	Ν	F	×	×	NL: number of line is 2/1	37µs		
											F: font size is $5 \times 11/5 \times 8$			
Set					AC	AC	AC	AC	AC	AC	Set CGRAM address in address			
CGRAM	0	0	0	1	5	4	3	2	1	0	counter.	37µs		
Address														
Set				AC	AC	AC	AC	AC	AC	AC	Set DDRAM address in address			
DDRAM	0	0	1	6	5	4	3	2	1	0	counter.	37µs		
Address														

2.4 Display Command



Read Busy Flag and Address	0	1	BF	AC 6	AC 5	AC 4	AC 3	AC 2	AC 1	AC 0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0µs
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM).	37µs
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM).	37µs

Note:

Be sure the ST7066U is not in the busy state (BF=0) before sending an instruction from the MPU to the ST7066.

If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself.

Before checking BF, be sure to wait at least 80us.. Do not keep "E" always "High" for checking BF. Refer to Instruction Table for the list of each instruction execution time.



2.5 Character Pattern

CHARACTER PATTERN(SO/HO/EA,WA)

Lower 4 Bits	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
xxxx0000	CG RAM (1)			Ø	31	•		<u>۽</u>					-37	≣.	\odot	<u>ا</u>
xxxx0001	(2)		I	1	[]	0	-===	-::			==]-'	<u>ب</u>	Ċ.,		
xxxx0010	(3)		11	2		Pe	ŀ:)	F			I		1	.:-: [*]	₽₽	m
xxxx0011	(4)		#		<u> </u>	<u>.</u>	· <u></u> .	: .				<u>ر</u> ،	<u> </u>	1	: :: -	=:-:=
****0100	(5)		35	4	\square	T	<u> </u>	1 <u>.</u> .				<u> </u>	ŀ	1->	-	572
xxxx0101	(6)				<u> </u>	II	: : :	II				-1	 		3	
xxxx0110	(7)		8.	<u>.</u>	[IJ	- F -	ı			ņ]]]			j=	2
xxxx0111	(8)			7	G	Į, l	9	I., I				=			<u> </u>	71
xxxx1000	(1)		Ć	8		2	ŀ'n	3				<u> </u>	:#:	Ļ	I	34
xxxx1001	(2))	9	Ι	ا ب'	i	'::: !			-::-	'n	.!	11.	:	ا <u>…</u> ا
xxxx1010	(3)		:- [-:	:: ::	Т	<u>.</u>]	<u></u>]	• •	.	j	.
xxxx1011	(4)		[3	k:	Ľ	k	-:			:#	ŗ	!		:•:]=]
xxxx1100	(5)		:=		l	4	1	ľ			1-2	∷ !	·]	<u>.</u>	:	PH
xxxx1101	(6)]]	[**]						··	 	‡	
****1110	(7)				ŀ	····	ŀ"ı]					. .	•••	F	
xxxx1111	(8)										• :_•	'I	:"		<u> </u>	

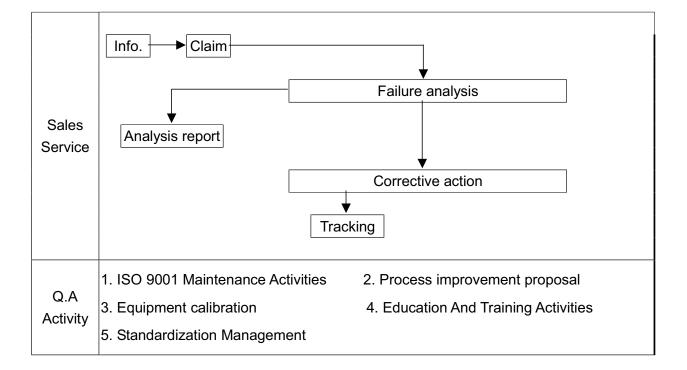


3. QUALITY ASSURANCE SYSTEM

Product Inventory Purchase R&D Manufacturing Item Customer Sales Q.A control control Survey Info. Marketing Request Inquiry & **Design evaluation** Design Quote Contract Design check Sample Approval Sample test Sample approval Pilot run & Reliability test Pilot Run & Specification preparation Mass Product Mass production Inspection Shipment Ship Out Ship out

3.1 Quality Assurance Flow Chart







3.2 Inspection Specification

Inspection Standard : MIL-STD-105E Table Normal Inspection Single Sampling Level $II \circ$ Equipment : Gauge \land MIL-STD \land Tester \land Sample \circ

IQC Defect Level : Major Defect AQL 0.65; Minor Defect AQL 1.0 \circ

FQC Defect Level : 100% Inspection -

OUT Going Defect Level : Sampling -

Specification :

ΝO	Item	Specification	Judge	Level
1	Part Number	Inconsistent with the P/N on the flow chart of production	N.G.	Major
2	Quantity	Inconsistent Q'TY with the flow chart of production	N.G.	Major
	Ele etre ele	Display short	N.G.	Major
	Electronic	Missing line	N.G.	Major
3	characteristics	Dot missing A $>$ 1/2 Dot size	N.G.	Major
	A=(L + W)÷2	No function	N.G.	Major
	A-(L'W).Z	Out put data error	N.G.	Major
		Material difference with flow chart	N.G.	Major
	Annoaranaa	LCD Assembled in opposite direction	N.G.	Major
	Appearance	Bezel assembled in opposite direction	N.G.	Major
	A=(L + W)÷2	Shadow within LCD V./A + 1.0 mm	N.G.	Major
4	A-(L+VV)÷2	Dirty particle A>0.4 mm	N.G.	Minor
-	Dirty particle (Include	Dirty particle length $>$ 3.0mm And 0.01mm < Width \leq 0.05mm (Width > 0.05mm Measure by area)	N.G.	Minor
	scratch bubble)	Without protective film	N.G.	Minor
		Conductive rubber over bezel	N.G.	Minor
		Burned PCB	N.G.	Major
		Green paint stripped & visible circuit A>1.0mm (Finish coat not counted in)	N.G.	Minor
	PCB Appearance	A particle across the circuit	N.G	Minor
5		Circuit split >1/2 Circuit width	N.G	Minor
	A=(L + W)÷2	Any circuit risen	N.G	Minor
		0.2mm <tin area="" a≦0.4mm<br="" ball="">And Q'TY>4 Pieces</tin>	N.G	Minor
		Tin ball area A>0.4mm	N.G	Minor



NO	Item	Specification	Judge	Level
		Too soft : Shape by touch changed	N.G.	Major
	Molding	Insufficient epoxy : IC circuit or IC pad visible	N.G.	Minor
6	appearance A=(L + W)÷2	Excessive epoxy : Diameter >20mm Or High>2.5mm	N.G.	Minor
		Pin hole through to IC and A>0.2mm	N.G.	Minor
		Angle between frame and TAB $>$ 45 $^\circ$ +10 $^\circ$	N.G.	Minor
7	Bezel appearance	Electroplate strip A $>$ 1.0mm (Top view only)	N.G.	Minor
	A=(L + W)÷2	Rust (Top view only)	N.G.	Minor
		Crack	N.G.	Minor
	De ablight als stris	Error backlight color	N.G.	Major
	Backlight electric	No function	N.G.	Major
8	characteristics	Any LED dot no function	N.G.	Major
	A=(L + W)÷2	PIN soldering without tin A $>$ 1/2 solder pad	N.G.	Minor
	A-(L · W)·Z	Solder PIN high > 1.5mm	N.G.	Minor
9	LCD Appearance A=(L + W)÷2	Polarize rise over V/A	N.G.	Minor
		Components mark unclearly	N.G.	Minor
		Components' distance more than 0.7mm firm the PCB	N.G.	Minor
10	Assembly parts A=(L + W)÷2	Error position ,not in center D>1/4W	N.G.	Minor
		Non- solder area > Twice solder area	N.G.	Minor
		Flux area A $>$ 1/4 solder area	N.G.	Minor
		Component broken	N.G.	Minor



4. RELIABILITY TEST

4.1 Reliability Test Condition

H.I No	Item		ondition						
		Storage at 80 ±2°C 96~100 l							
1	High Temperature Storage	surrounding temperature, then storage at normal condition 4hrs							
	Low Tomporaturo	Storage at -30 $\pm 2^{\circ}$ C 96~100 hrs							
2	Low Temperature Storage	surrounding temperature, the 4hrs	n storage at normal condition						
3	High Temperature /Humidity Storage	 1.Storage 96~100 hrs 60±2°C, 90~95%RH surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer). or 2.Storage 96~100 hrs 40±2°C, 90~95%RH surrounding temperature, then storage at normal condition 4 hrs. 							
			→ 70°C → 25°C						
4	Temperature Cycling	(30mins) (5mins) (30mins) (5mins) 10 Cycle							
5	Vibration	10~55Hz(1 minute)1.5mm X,Y and Z direction * (each 2hrs)							
6	ESD Test	Air Discharge: Apply 6 KV with 5 times discharge for each polarity +/	Contact Discharge: Apply 250V with 5 times discharge for each polarity +/						
		Testing location: Around the face of LCD.	Testing location: 1.Apply to bezel. 2.Apply to Vdd, Vss.						
		Packing Weight (Kg)	Drop Height (cm)						
		0 ~ 45.4	122						
7.	Drop Test	45.4 ~ 90.8	76						
		90.8 ~ 454	61						
		Over 454	46						



5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks , be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module , be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So, please handle it very carefully ,do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth , as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands , this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is $280\pm10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM .

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is $25^{\circ}C \pm 5^{\circ}C$ and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush , shake , or jolt the module.

5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life